

## YDS-MIPI-OV5640-1B V3.6

### 5MP OmniVision OV5640-1B MIPI and DVP Parallel Interface Auto Focus Camera Module



Front View



Back View

#### Specifications

<b>Camera Module No.</b>	<b>YDS-MIPI-OV5640-1B V3.6</b>
<b>Resolution</b>	5MP
<b>Image Sensor</b>	OV5640-1B
<b>Sensor Type</b>	1/4"
<b>Pixel Size</b>	1.4 um x 1.4 um
<b>EFL</b>	3.29 mm
<b>F.NO</b>	2.80
<b>Pixel</b>	2592 x 1944
<b>View Angle</b>	68.7°(DFOV) 58.1°(HFOV) 45.0°(VFOV)
<b>Lens Dimensions</b>	8.50 x 8.50 x 5.07 mm
<b>Module Size</b>	100.00 x 8.50 mm
<b>Module Type</b>	Auto Focus
<b>Interface</b>	MIPI and DVP Parallel
<b>Auto Focus VCM Driver IC</b>	Embedded
<b>Lens Model</b>	YDS-LENS-M5101
<b>Lens Type</b>	650nm IR Cut
<b>Operating Temperature</b>	-30°C to +70°C
<b>Mating Connector</b>	DF30FC-40DS-0.4V



## YDS-MIPI-OV5640-1B V3.6 5MP OmniVision OV5640-1B MIPI and DVP Parallel Interface Auto Focus Camera Module



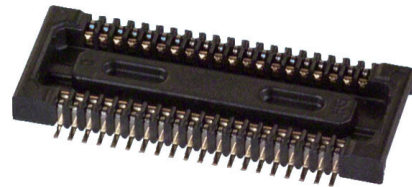
Top View



Side View



Bottom View

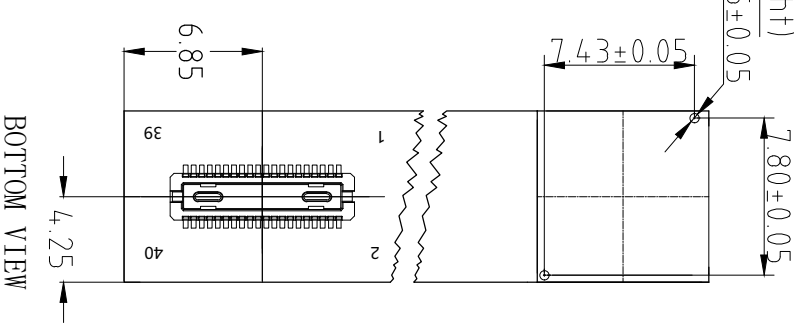
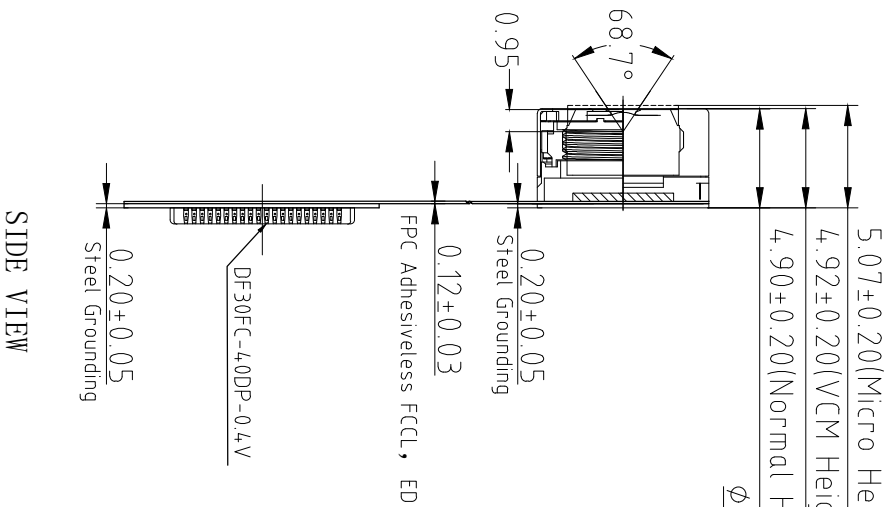
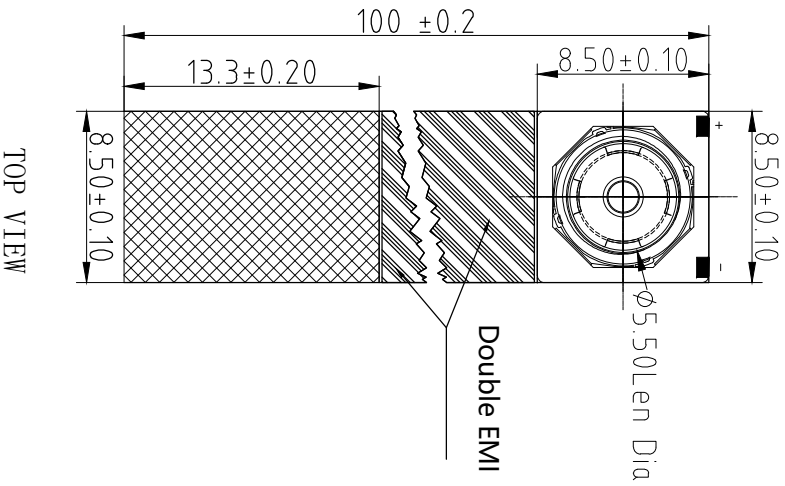
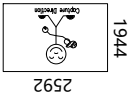


Mating Connector

# ROHS

## PIN SIGNAL

1	AGND
2	AF-AGND
3	STROBE
4	AF-VDD2.8V
5	SDA
6	NC
7	SCL
8	AVDD2.8V
9	RESET
10	NC
11	PCLK
12	NC
13	VSYNC
14	FRFX
15	HREF
16	MDP2
17	PVDN1
18	MDN2
19	D9
20	DGND
21	D8
22	MCP
23	D7
24	MCN
25	D6
26	DGND
27	D5
28	MDP1
29	D4
30	MDN1
31	D3
32	DGND
33	D2
34	XCLK
35	D1
36	DVDD1.5V
37	D0
38	DOVDD1.8V
39	DGND
40	DGND



TOP VIEW

SIDE VIEW

BOTTOM VIEW

### Parameters:

#### 1、Sensor specification:

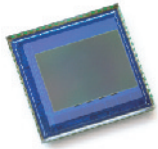
Image Sensor: OV5640-1B  
 Pixel: 1.4um×1.4um  
 Lens Type: 1/4  
 Important Voltage Description: DVDD1.5V (external power supply);

#### 2、Lens specification:

FOV: 68.7°(D),58.1°(H),45°(V)  
 F/NO: 2.8  
 TV distortion: <1.0%  
 Focal length: 3.29mm  
 Composition: 4P+IR FILTER  
 IR Cut Coating: 650nm±10nm@50%

Version	Information	Date
V3.2	Change VCM	12-5-2016
V3.6	Change lens and connector	9-11-2020

Designed By	Kevin	Model Name:	MIP1-OV5640-1B V3.6
Checked By	Aouly_Yan	Projection Type:	Third Angle
		Unit:	mm
		Scale:	1:1
		Material:	-----
		Sheet:	1 of 1
		Version:	1/0



# OV5640 5-megapixel product brief



## 1/4-inch, 5-Megapixel SOC Image Sensor Optimized for High-Volume Mobile Markets



available in  
a lead-free  
package

The OV5640 delivers a complete 5-megapixel camera solution on a single chip, aimed at offering cost efficiencies that serve the high-volume autofocus (AF) camera phone market. The system-on-a-chip (SOC) sensor features OmniVision's 1.4 micron OmniBSI™ backside illumination architecture to deliver excellent pixel performance and best-in-class low-light sensitivity, while enabling ultra compact camera module designs of 8.5 mm x 8.5 mm with <6 mm z-height. The OV5640 provides the full functionality of a complete camera, including anti-shake technology, AF control, and MIPI while being easier to tune than two-chip solutions, making it an ideal choice in terms of cost, time-to-market and ease of platform integration.

The OV5640 enables 720p HD video at 60 frames per second (fps) and 1080p HD video at 30 fps with complete user control over formatting and output data transfer. The 720p/60 HD video is captured in full field of view (FOV) with 2 x 2 binning, which doubles the sensitivity and improves the signal-to-noise ratio (SNR). Additionally, a unique post-binning re-sampling filter function removes zigzag artifacts around slant edges and minimizes spatial artifacts to deliver even sharper, crisper

color images. To further improve camera performance and user experience, the OV5640 features an internal anti-shake engine for image stabilization, and it supports Scalado™ tagging for faster image preview and zoom.

The OV5640 offers a digital video port (DVP) parallel interface and a high-speed dual lane MIPI interface, supporting multiple output formats. An integrated JPEG compression engine simplifies data transfer for bandwidth-limited interfaces. The sensor's automatic image control functions include automatic exposure control (AEC), automatic white balance (AWB), automatic band filter (ABF), 50/60 Hz automatic luminance detection, and automatic black level calibration (ABLC). The OV5640 delivers programmable controls for frame rate, AEC/AGC 16-zone size/position/weight control, mirror and flip, cropping, windowing, and panning. It also offers color saturation, hue, gamma, sharpness (edge enhancement), lens correction, defective pixel canceling, and noise canceling to improve image quality.

Find out more at [www.ovt.com](http://www.ovt.com).

## applications

- cellular phones
- toys
- PC multimedia
- digital still cameras

## ordering information

- **OV05640-A71A-1B** (color, lead-free)  
71-pin CSP

## features

- 1.4  $\mu\text{m}$  x 1.4  $\mu\text{m}$  pixel with OmniBSI technology for high performance (high sensitivity, low crosstalk, low noise, improved quantum efficiency)
- optical size of 1/4"
- automatic image control functions: automatic exposure control (AEC), automatic white balance (AWB), automatic band filter (ABF), automatic 50/60 Hz luminance detection, and automatic black level calibration (ABLC)
- programmable controls for frame rate, AEC/AGC 16-zone size/position/weight control, mirror and flip, cropping, windowing, and panning
- image quality controls: color saturation, hue, gamma, sharpness (edge enhancement), lens correction, defective pixel canceling, and noise canceling
- support for output formats: RAW RGB, RGB565/555/444, CCIR656, YUV422/420, YCbCr422, and compression
- support for video or snapshot operations
- support for internal and external frame synchronization for frame exposure mode
- support for LED and flash strobe mode
- support for horizontal and vertical sub-sampling, binning
- support for minimizing artifacts on binned image
- support for data compression output
- support for anti-shake
- standard serial SCCB interface
- digital video port (DVP) parallel output interface and dual lane MIPI output interface
- embedded 1.5V regulator for core power
- programmable I/O drive capability, I/O tri-state configurability
- support for black sun cancellation
- support for images sizes: 5 megapixel, and any arbitrary size scaling down from 5 megapixel
- support for auto focus control (AFC) with embedded AF VCM driver
- embedded microcontroller
- suitable for module size of 8.5 x 8.5 x <6mm with both CSP and RW packaging

## key specifications (typical)

- **active array size:** 2592 x 1944
- **power supply:**
  - core: 1.425 ~ 1.675V (with embedded 1.5V regulator)
  - analog: 2.6 ~ 3.0V (2.8V typical)
  - I/O: 1.8V / 2.8V
- **power requirements:**
  - active: 140 mA
  - standby: 20  $\mu\text{A}$
- **temperature range:**
  - operating: -30°C to 70°C junction temperature (see [table 8-2](#))
  - stable image: 0°C to 50°C junction temperature (see [table 8-2](#))
- **output formats:** 8-/10-bit RGB RAW output
- **lens size:** 1/4"
- **lens chief ray angle:** 24° (see [figure 10-2](#))
- **input clock frequency:** 6~27 MHz
- **max S/N ratio:** 36 dB
- **dynamic range:** 68 dB @ 8x gain
- **maximum image transfer rate:**
  - QSXGA (2592x1944): 15 fps
  - 1080p: 30 fps
  - 1280x960: 45 fps
  - 720p: 60 fps
  - VGA (640x480): 90 fps
- **sensitivity:** 600 mV/Lux-sec
- **shutter:** rolling shutter / frame exposure
- **maximum exposure interval:** 1964 x  $t_{\text{ROW}}$
- **pixel size:** 1.4  $\mu\text{m}$  x 1.4  $\mu\text{m}$
- **dark current:** 8 mV/s @ 60°C junction temperature
- **image area:** 3673.6  $\mu\text{m}$  x 2738.4  $\mu\text{m}$
- **package dimensions:** 5985  $\mu\text{m}$  x 5835  $\mu\text{m}$

## YDS-LENS-M5101

SPECIFICATION		
1. SENSOR SIZE	1/4" (5M CSP)	
2. MAX IMAGE CIRCLE	φ4.90mm	
3. TOTAL TRACK	4.18±0.1mm	
4. BFL	3.29mm	
5. OPTICAL BFL	1.43mm	
6. MECHANICAL BFL	0.85mm	
7. F/NO	2.8±5%	
8. VIEW OF FIELD	VERTICAL	45.0° (γ=1.36)
	HORIZONTAL	58.1° (γ=1.814)
	DIAGONL	68.7° (γ=2.268)
9. OPTICAL DISTORTION	<1.0%	
10. TV DISTORTION	<1.0%	
11. RELATIVE ILLUMINATION	>42.3%	
12. CONSTRUCTION	4F+IR FILTER	
13. CHIEF RAY ANGLE	<25°	
14. CUT FREQUENCY AT 50%	650±10nm	
15. THREAD	M6.0X0.35P	
16. IMAGE QUALITY	AXIS	330lp/mm
	0.7Y	200lp/mm
17. APPEARANCE QUALITY (Scratch/Di <sub>2</sub> )	CENTER	20/10
	EDGE	40/20

NO	MODIFY CONTENT	NAME	DATE	ANGLE	DIM	TYPE	UNIT	MATERIAL	SCALE	APPROVED BY	FINISH	DATE	LOCATION	REV
1									8 : 1			2013.05.03		A-00

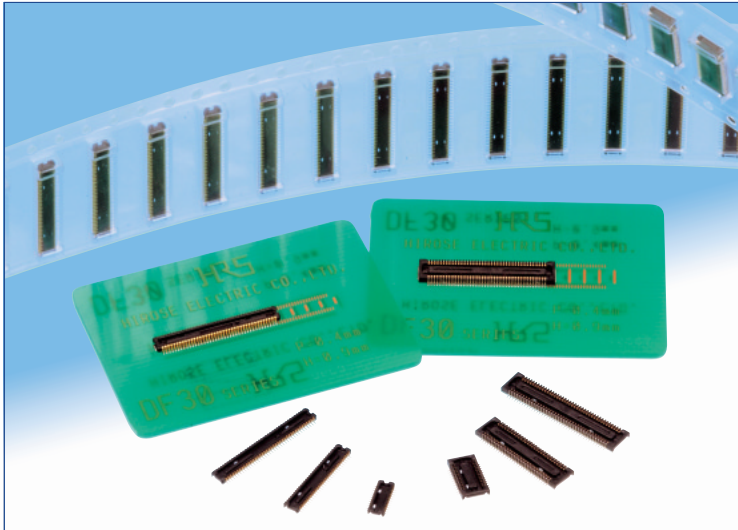
**NOTE:**

- 镜头表面不可有油污、灰尘、毛丝等异物。
- 镜头配VCM锁附高度为 4.7±0.1mm, 扭力为20—60gf.cm。
- 镜头承受推力为≥2.0kg。
- 镜头品质参数需符合图中要求。

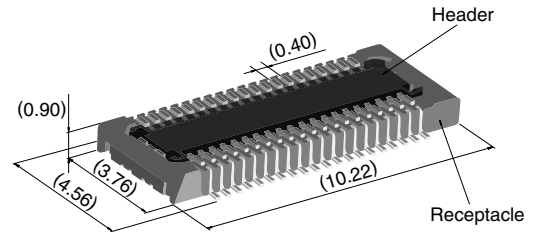
The drawing shows a lens with a diameter of 5.40mm and a central hole of 4.7mm. The front view shows chamfered edges with R0.15 radii and 4-45 degree chamfers. The side view shows a total thickness of 4.18±0.10mm, with a mechanical back focal length (BFL) of 0.85mm and an optical BFL of 1.43mm. The lens is mounted on a base with an M6.0X0.35P thread. The drawing also indicates an IR CUT filter and an IMAGE PLANE.

# 0.4 mm Pitch, 0.9 mm Height, Board-to-Board / Board-to-FPC Connectors

## DF30 Series



### Extremely small size



40 positions shown

### Overview

Continuous miniaturization and increased component density on PCB created demand for extremely low profile connectors. This series is addition of a new extremely low profile connectors to Hirose's wide range of high reliability board-to-board/board-to-FPC connection solutions.

### Features

#### 1. Contact reliability

Concentration of the contact's normal forces at the single point assures good contact wipe and electrical reliability, while confirming the fully mated condition with a definite tactile click.

#### 2. Self alignment

Recognizing the difficulties of mating extremely small connectors in limited spaces the connectors will self align in horizontal axis within 0.3 mm.

#### 3. Automatic board placement

Packaged on tape-and-reel the plug and headers have sufficiently large flat areas to allow pick-up with vacuum nozzles of automatic placement equipment.

#### 4. Variety of contact positions and styles

Available in standard contact positions of: 20, 22, 24, 30, 34, 40, 50, 60, 70 and 80 with and without metal fittings. Addition of metal fittings does not affect external dimensions of the connectors.

Smaller contact positions are also available.

#### 5. Support for continuity test connector

Connectors which have increased insertion and removal durability are available for continuity tests. Contact your Hirose sales representative for details.

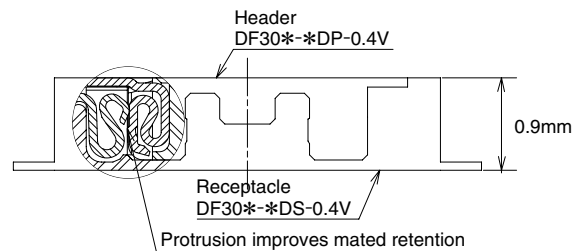
### Applications

Cellular phones, PDA's, mobile computers, digital cameras, digital video cameras, and other devices demanding high reliability connections in extremely limited spaces.

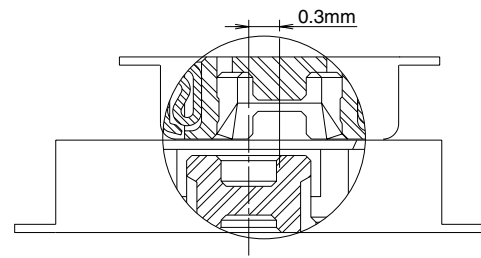
#### Low profile

#### Increased mated retention

#### High contact reliability



### Self alignment





## Product Specifications

Rating	Rated current 0.3A	Operating temperature range : -35°C to 85°C (Note 1)	Storage temperature range -10°C to 60°C (Note 2)
	Rated voltage 30V AC	Operating humidity range : Relative humidity 20% to 80%	Storage humidity range Relative humidity 40% to 70% (Note 2)

Item	Specification	Conditions
1. Insulation resistance	50 MΩ min.	100V DC
2. Withstanding voltage	No flashover or insulation breakdown.	100V AC / one minute
3. Contact resistance	100 mΩ max.	100 mA
4. Vibration	No electrical discontinuity of 1 μs or more	Frequency: 10 to 55 Hz, single amplitude of 0.75mm, 2 hours, 3 axis
5. Humidity	Contact resistance: 100 mΩ max. Insulation resistance: 25 MΩ min.	96 hours at temperature of 40°C±2°C and RH of 90% to 95%
6. Temperature cycle	Contact resistance: 100 mΩ max. Insulation resistance: 50 MΩ min.	Temperature: -55°C→+5°C to +35°C→+85°C→+5°C to +35°C Duration: 30→10→30→10(Minutes) 5 cycles
7. Durability (insertions/withdrawals)	Contact resistance: 100 mΩ max.	50 cycles(Connector for conductivity tests: 500 cycles)
8. Resistance to soldering heat	No deformation of components affecting performance.	Reflow: At the recommended temperature profile Manual soldering: 300°C for 3 seconds

Note 1: Includes temperature rise caused by current flow.

Note 2: The term "storage" refers to products stored for long period of time prior to mounting and use. Operating temperature range and humidity range covers non-conducting condition of installed connectors in storage, shipment or during transportation.

## Materials and Finishes

Connectors	Component	Material	Finish	Remarks
Receptacles and Headers	Insulator	LCP	Color : Black	UL94V-0
	Contacts	Phosphor bronze	Gold plated	————
	Metal fittings	Phosphor bronze	Tin-copper plated	————

## Ordering information

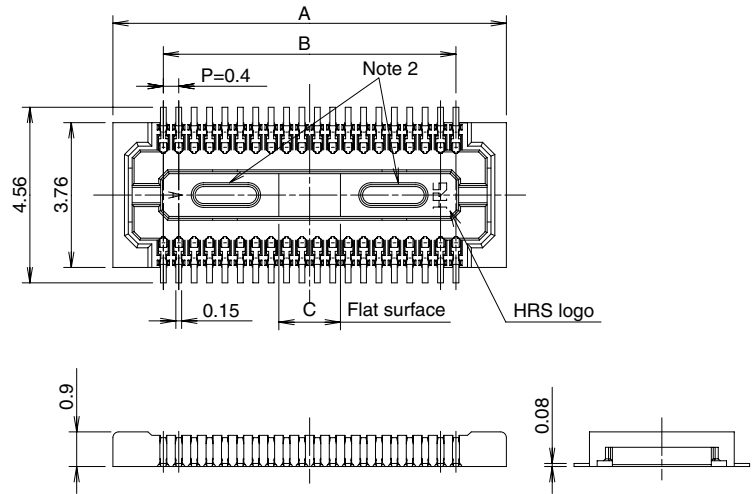
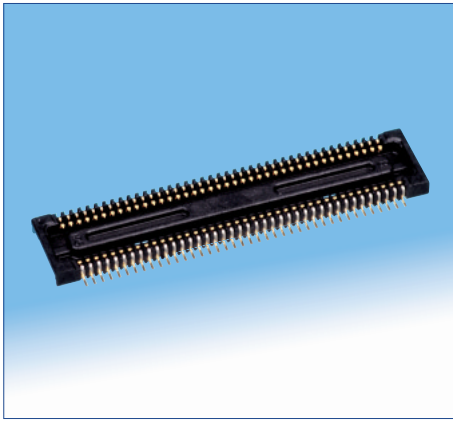
### Receptacles and Headers

**DF30**   **FC** -   **\***   **DS - 0.4**   **V**   **(\*\*)**  
①   ②   ③   ④   ⑤   ⑥   ⑦

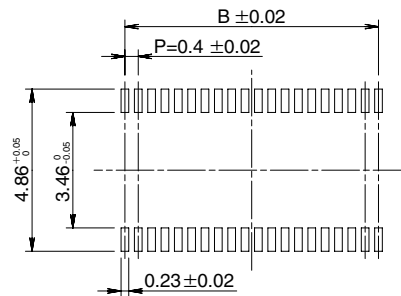
① Series name: DF30	⑤ Contact pitch: 0.4 mm
② Configuration FB: With metal fittings, without bosses FC: Without metal fittings, without bosses CJ: Connector for conductivity tests	⑥ Termination section V: Straight SMT
③ Number of positions: 20, 22, 24, 30, 34, 40, 50, 60, 70, 80	⑦ Packaging (81): Embossed tape packaging (5,000 pieces per reel) (82): Embossed tape packaging (1,000 pieces per reel)
④ Connector type DS: Double row receptacle DP: Double row header	



## ■ Receptacles (without metal fittings)



## ◆ Recommended PCB mounting pattern



Recommended solder paste thickness: 120  $\mu$ m

[Specification number] -\*\*, (\*\*)  
(81): Embossed tape packaging (5,000 pieces per reel)

\* Tolerances non- accumulative.

Unit: mm

Part Number	CL No.	Number of contacts	A	B	C
DF30FC-20DS-0.4V(**)	CL684-1109-8-**	20	6.22	3.6	1.2
DF30FC-22DS-0.4V(**)	CL684-1110-7-**	22	6.62	4.0	1.2
DF30FC-24DS-0.4V(**)	CL684-1111-0-**	24	7.02	4.4	1.2
DF30FC-30DS-0.4V(**)	CL684-1112-2-**	30	8.22	5.6	1.2
DF30FC-34DS-0.4V(**)	CL684-1113-5-**	34	9.02	6.4	1.36
DF30FC-40DS-0.4V(**)	CL684-1078-6-**	40	10.22	7.6	1.6
DF30FC-50DS-0.4V(**)	CL684-1114-8-**	50	12.22	9.6	2.0
DF30FC-60DS-0.4V(**)	CL684-1082-3-**	60	14.22	11.6	2.4
DF30FC-70DS-0.4V(**)	CL684-1115-0-**	70	16.22	13.6	2.8
DF30FC-80DS-0.4V(**)	CL684-1116-3-**	80	18.22	15.6	3.2

Note 1: Order by number of reels.

Note 2: Receptacles with 24 or fewer contacts positions will not have recessed areas.



# YDS CAMERA MODULE

*your best camera partner*

## Camera Module Pinout Definition Reference Chart

OmniVision	Sony	Samsung	On-Semi	Aptina	Himax	GalaxyCore	PixArt	SmartSens	Sensors
Pin Signal		Description							
DGND GND		ground for digital circuit							
AGND		ground for analog circuit							
PCLK DCK		DVP PCLK output							
XCLR PWDN XSHUTDOWN STANDBY		power down active high with internal pull-down resistor							
MCLK XVCLK XCLK INCK		system input clock							
RESET RST		reset active low with internal pull-up resistor							
NC NULL		no connect							
SDA SIO_D SIOD		SCCB data							
SCL SIO_C SIOC		SCCB input clock							
VSYNC XVS FSYNC		DVP VSYNC output							
HREF XHS		DVP HREF output							
DOVDD		power for I/O circuit							
AFVDD		power for VCM circuit							
AVDD		power for analog circuit							
DVDD		power for digital circuit							
STROBE FSTROBE		strobe output							
FSIN		synchronize the VSYNC signal from the other sensor							
SID		SCCB last bit ID input							
ILPWM		mechanical shutter output indicator							
FREQ		frame exposure / mechanical shutter							
GPIO		general purpose inputs							
SLASEL		I2C slave address select							
AFEN		CEN chip enable active high on VCM driver IC							
<b>MIPI Interface</b>									
MDN0 DN0 MD0N DATA_N DMO1N		MIPI 1st data lane negative output							
MDP0 DP0 MD0P DATA_P DMO1P		MIPI 1st data lane positive output							
MDN1 DN1 MD1N DATA2_N DMO2N		MIPI 2nd data lane negative output							
MDP1 DP1 MD1P DATA2_P DMO2P		MIPI 2nd data lane positive output							
MDN2 DN2 MD2N DATA3_N DMO3N		MIPI 3rd data lane negative output							
MDP2 DP2 MD2P DATA3_P DMO3P		MIPI 3rd data lane positive output							
MDN3 DN3 MD3N DATA4_N DMO4N		MIPI 4th data lane negative output							
MDP3 DP3 MD3P DATA4_P DMO4P		MIPI 4th data lane positive output							
MCN CLKN CLK_N DCKN		MIPI clock negative output							
MCP CLKP MCP CLK_P DCKN		MIPI clock positive output							
<b>DVP Parallel Interface</b>									
D0 DO0 Y0		DVP data output port 0							
D1 DO1 Y1		DVP data output port 1							
D2 DO2 Y2		DVP data output port 2							
D3 DO3 Y3		DVP data output port 3							
D4 DO4 Y4		DVP data output port 4							
D5 DO5 Y5		DVP data output port 5							
D6 DO6 Y6		DVP data output port 6							
D7 DO7 Y7		DVP data output port 7							
D8 DO8 Y8		DVP data output port 8							
D9 DO9 Y9		DVP data output port 9							
D10 DO10 Y10		DVP data output port 10							
D11 DO11 Y11		DVP data output port 11							

[www.YDSCAM.com](http://www.YDSCAM.com) [sales@ydscam.com](mailto:sales@ydscam.com) Phone (WeChat, QQ): (+86) 177 2732 6718

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## Cameras Applications





## Camera Reliability Test

Reliability Inspection Item		Testing Method	Acceptance Criteria	
Category	Item			
Environmental	Storage Temperature	High 60°C 96 Hours	Temperature Chamber	No Abnormal Situation
		Low -20°C 96 Hours	Temperature Chamber	No Abnormal Situation
	Operation Temperature	High 60°C 24 Hours	Temperature Chamber	No Abnormal Situation
		Low -20°C 24 Hours	Temperature Chamber	No Abnormal Situation
	Humidity	60°C 80% 24 Hours	Temperature Chamber	No Abnormal Situation
	Thermal Shock	High 60°C 0.5 Hours Low -20°C 0.5 Hours Cycling in 24 Hours	Temperature Chamber	No Abnormal Situation
Physical	Drop Test (Free Falling)	Without Package 60cm	10 Times on Wood Floor	Electrically Functional
		With Package 60cm	10 Times on Wood Floor	Electrically Functional
	Vibration Test	50Hz X-Axis 2mm 30min	Vibration Table	Electrically Functional
		50Hz Y-Axis 2mm 30min	Vibration Table	Electrically Functional
		50Hz Z-Axis 2mm 30min	Vibration Table	Electrically Functional
	Cable Tensile Strength Test	Loading Weight 4 kg 60 Seconds Cycling in 24 Hours	Tensile Testing Machine	Electrically Functional
Electrical	ESD Test	Contact Discharge 2 KV	ESD Testing Machine	Electrically Functional
		Air Discharge 4 KV	ESD Testing Machine	Electrically Functional
	Aging Test	On/Off 30 Seconds Cycling in 24 Hours	Power Switch	Electrically Functional
	USB Connector	On/Off 250 Times	Plug and Unplug	Electrically Functional



## Camera Inspection Standard

Inspection Item		Inspection Method	Standard of Inspection		
Category	Item				
Appearance	FPC/ PCB	Color	The Naked Eye	Major Difference is Not Allowed.	
		Be Torn/Chopped	The Naked Eye	Copper Crack Exposure is Not Allowed.	
		Marking	The Naked Eye	Clear, Recognizable (Within 30cm Distance)	
	Holder	Scratches	The Naked Eye	The Inside Crack Exposure is Not Allowed	
		Gap	The Naked Eye	Meet the Height Standard	
		Screw	The Naked Eye	Make Sure Screws Are Presented (If Any)	
		Damage	The Naked Eye	The Inside Crack Exposure is Not Allowed	
	Lens	Scratch	The Naked Eye	No Effect On Resolution Standard	
		Contamination	The Naked Eye	No Effect On Resolution Standard	
		Oil Film	The Naked Eye	No Effect On Resolution Standard	
		Cover Tape	The Naked Eye	No Issue On Appearance.	
	Function	Image	No Communication	Test Board	Not Allowed
			Bright Pixel	Black Board	Not Allowed In the Image Center
Dark Pixel			White board	Not Allowed In the Image Center	
Blurry			The Naked Eye	Not Allowed	
No Image			The Naked Eye	Not Allowed	
Vertical Line			The Naked Eye	Not Allowed	
Horizontal Line			The Naked Eye	Not Allowed	
Light Leakage			The Naked Eye	Not Allowed	
Blinking Image			The Naked Eye	Not Allowed	
Bruise			Inspection Jig	Not Allowed	
Resolution			Chart	Follows Outgoing Inspection Chart Standard	
Color			The Naked Eye	No Issue	
Noise			The Naked Eye	Not Allowed	
Corner Dark			The Naked Eye	Less Than 100px By 100px	
Color Resolution			The Naked Eye	No Issue	
Dimension	Height	The Naked Eye	Follows Approval Data Sheet		
	Width	The Naked Eye	Follows Approval Data Sheet		
	Length	The Naked Eye	Follows Approval Data Sheet		
	Overall	The Naked Eye	Follows Approval Data Sheet		

## YDSCAM Package Solutions

YDS Camera Module



Complete with Lens Protection Film



Tray with Grid and Space



Place Cameras on the Tray





## YDSCAM Package Solutions

Full Tray of Cameras



Cover Tray with Lid



Place Tray into Anti-Static Bag



Vacuum the Anti-Static Bag





## YDSCAM Package Solutions

### Sealed Vacuum Anti-Static Bag with Labels

1. Model and Description 2. Quantity 3. Manufacturing Date Code 4. Caution



## YDSCAM Package Solutions

Place Foam Sheets Between Tray Bags



Foam Sheets are Larger Than Trays



Place Foam Sheets and Trays into Box



Foam Sheets are Tightly Fitting in Box



Seal the Carbon Box



Label the Carbon Shipping Box







## YDSCAM Package Solutions

USB Camera Module

Complete with Lens Protection Film



Place Camera Sample into Anti-Static Bag

Place USB Cameras into Tray



Seal the Tray with Anti-Static Bag

Label the Carbon Shipping Box



## YDSCAM Package Solutions

Place Camera Sample into Anti-Static Bag



Place Connectors into Anti-Static Bag



Label the Sample Bags



Place Connectors into Reel



Place Samples into the Carbon Box



Place Connectors into the Carbon Box







# YDS CAMERA MODULE

*your best camera partner*

## Company YDSCAM

YingDeShun Co. Ltd. (YDS) was established in 2017, a next-generation technology driven manufacturer specialized in research, design, and produce of audio and video products. YDS is occupying 20,000 square feet automated plants with 100 employees of annual throughput 30,000,000 units cameras.

YDS provides OEM, ODM design, contract manufacturing, and builds the camera products. You may provide the requirements to us, even with a hand draft, our sales and engineering work together to meet your needs. We consider ourselves your last-term partner in developing practical and innovative solutions.

Our team covers everything from initial concept development to mass produced product. YDS specializes in customized camera design, raw material, electronic engineering, firmware/software development, product testing, and packing design. Our experienced strategic supply systems offer a robust and dependable manufacturing capacity for orders of various sizes.



## Limited Warranty

YDS provides the following limited warranty if you purchased the Product(s) directly from YDS company or from YDS's website [www.YDSCAM.com](http://www.YDSCAM.com). Product(s) purchased from other sellers or sources are not covered by this Limited Warranty. YDS guarantees that the Product(s) will be free from defects in materials and workmanship under normal use for a period of one (1) year from the date you receive the product ("Warranty Period").

For all Product(s) that contain or develop material defects in materials or workmanship during the Warranty Period, YDS will, at its sole option, either: (i) repair the Product(s); (ii) replace the Product(s) with a new or refurbished Product(s) (replacement Product(s) being of identical model or functional equivalent); or (iii) provide you a refund of the price you paid for the Product(s).

This Limited Warranty of YDS is solely limited to repair and/or replacement on the terms set forth above. YDS is not reliable or responsible for any subsequent events.



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## YDS Strength

### Powerful Factory



### Professional Service



### Promised Delivery



[www.YDSCAM.com](http://www.YDSCAM.com) [sales@ydscam.com](mailto:sales@ydscam.com) Phone (WeChat, QQ): (+86) 177 2732 6718

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